

WHAT IS CLAIMED IS:

1. A method of manufacturing circuit devices, comprising:

preparing a substrate by laminating a first conductive film and a second conductive film to cover a principle surface of the first conductive film;

covering said second conductive film with a photoresist layer in a desirable pattern and having an inclined surface at opening portions;

selectively forming a conductive wiring layer at the opening portions of said photoresist layer and providing an inverted inclined surface around said conductive wiring layer;

removing said second conductive film by use of said conductive wiring layer as a mask;

fixedly fitting semiconductor elements on said first conductive film and electrically connecting electrodes of said semiconductor elements with predetermined parts of said conductive wiring layer;

covering said semiconductor elements with a sealing resin layer and making said sealing resin layer produce an anchoring effect at said inverted inclined surface of said conductive wiring layer; and

removing said first conductive film to expose said second conductive film positioned on the rear surface of said sealing resin layer and said conductive wiring layer.

2. The method of Claim 1, wherein said second conductive film is formed by silver electroplating.

3. The method of Claim 1, wherein said photoresist layer is heat-treated after development so as to form an inclined surface at said opening portions.

4. The method of Claim 1, wherein as said photoresist layer, a positive photoresist layer is used, and an inclined surface is formed by use of inferior resolution during development.

5. The method of Claim 1, wherein said conductive wiring layer is formed at said opening portion by copper electroplating while using said first conductive film as an electrode.

6. The method of Claim 1, wherein an etching solution for said second conductive film is an iodine-based solution.

7. The method of Claim 1, wherein said second conductive film and said sealing resin layer remaining when said first conductive film is etched are used as an etching stopper.

8. The method of Claim 6, wherein a solution containing ferric chloride or cupric chloride is used as a solution to perform said etching.

9. The method of Claim 1, wherein external electrodes are formed by adhering a brazing filler material to the remaining second conductive film.